SPECIFICATION FOR CONNECTOR USED FOR FPC/FFC WITH 1mm CONTACT SPACING COPING WITH AUTOMATIC MOUNTING & SMT SFW_ _R-1/2STE_

1. SCOPE

This specification covers the requirements for the connector (SFW__R-1/2STE_) with 1mm spacing to which the edge of FPC(Flexible Printed Circuit) and FFC(Flexible Flat Cable) can be connected by Zero-Insertion-Force method and which copes with automatic mounting and SMT.

2. APPICABLE STANDARDS

JIS	С	5402	Method for Test of Connectors for Electronic	Equipment
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- JIS C 0806 Packaging of Electronic Components on Continuous Tapes (Surface Mount Components)
- UL 94 TESTS FOR FLAMMABILITY OF PLASTIC MATERIALS FOR PARTS IN DEVICES AND APPLIANCES.

3. CATALOG No. STRUCTURE

	SFW	20	R	_	1	ST	E1
Series							
Number of Contacts							
Right Angle							
For FPC/FFC, Contact direction —							
1 : Lower contact type							
2: Upper contact type							
Cope with automatic mounting & SMT —							
Plastic Tape Packaging							

- 4. CONNECTOR SHAPE, DIMENSIONS AND MATERIALS See attached drawings.
- 5. ACCOMMODATED CONDUCTORS (FPC/FFC) See attached drawings.
- 6. PACKAGING CONDITION See attached drawings.
- 7. RECOMMENDED MOUNTING PATTERN DIMENSIONS See attached drawings.

8. RATING

8-1. Voltage: A.C.100V D.C.100V

- 8-2. Current: A.C.1A D.C.1A (Refer to the following note.)
- 8-3. Operating Temperature : -55°C ~ +85°C (Including terminal temperature rises)

NOTE

Allowable maximum current for one contact is 1A. Total allowable current for a whole connector is the value which is shown in the following figure.



9. PERFORMANCE CHARACTERISTICS

9-1. Electrical Performance

No.	Test Item	Test Method	Requirements
		1)Measure contact resistance between V_1 - V_2 by voltage drop method by the following circuit by mating accommodated conductor stipulated in clause 5 after reflow soldering the connector on the P.CB. and cleaning flux dregs.	 Initial value : Less than 30mΩ Contact resistance after the test is in accordance with the value specified in each test item.
9-1-1	Contact resistance	Connector Connductor V1 Smm V1 Pattern V2 P.C.B. Smm P.C.B.	
		2)Open circuit voltage : Less than A.C.20mV 3)Test current : Less than A.C.20mA	
9-1-2	Insulation resistance	 Measure insulation resistance between adjacent contacts in a connector individual. Test voltage: D.C.500V Read value one minute after applying test voltage. 	1)More than 500MΩ
9-1-3	Dielectric withstanding voltage	1)For one minute, apply A.C.500V between adjacent contacts in a connector individual.2)Set current: A.C.1mA	1)Free from any short circuit and insulation breakdown.

9-2. Mechanical Performance

No.	Test Item	Test Method	Requirements
		1)Measure contact resistance before and	1)Initial contact resistance
	Durability (Slider operation)	after the test by the method in clause	: Less than $30m\Omega$
		9-1-1 by mating the accommodated.	2)Contact resistance after the
9-2-1		2)Number of slider open and close	test: Less than $50m\Omega$
		: 20 times	3)Free from any defect such as
		(Insert and extract the conductor	break etc. on the connector
		for each opening of the slider.)	and conductor.
	Vibration (Sinusoidal)	JIS C 0040	
		1)Frequency range: 10 ~ 500Hz	1)During the test, no circuit
		2)Amplitude: 0.75mm	opening for more than 1µs.
9-2-2		or Acceleration : 100m/s ²	2)Free from any defect such as
		3)Sweep rate: 1 octave/minute	break, deformation, loosing
		4)Kind of test: Sweep endurance test	and falling off etc. on each
		5)Test time: 10 cycles	portion of the connector.

9-3. Environmental Performance

No.	Test Item	Test Method	Requirements
9-3-1	Damp heat (Steady state)	 JIS C 0022 1)Measure contact resistance before and after the test by the method in clause 9-1-1 by using the accommodated conductor specified in clause 5. 2)Measure insulation resistance after the test by the method in clause 9-1-2. 3)Bath temperature: 40°C 4)Bath humidity: 90 ~ 95% (relative humidity) 5)Period of exposure: 48 hours 6)Expose conductor and connector in mated condition and leave them under normal temperature. (Without insertion and separation) 	 Initial contact resistance : Less than 30mΩ Contact resistance after the test: Less than 50mΩ Insulation resistance after the test: More than 100MΩ
9-3-2	Salt spray	 JIS C 0023 1)Measure contact resistance before and after the test according to the method in clause 9-1-1 by using accommodated conductor specified in clause 5. 2)Salt solution concentration: 5% 3)Period of exposure: 48 hours 4)Expose conductor and connector in mated condition and leave them under normal temperature after posttreatment. 	 Initial contact resistance : Less than 30mΩ Contact resistance after the test: Less than 50mΩ
9-3-3	Change of temperature	JIS C 0025 1)Measure contact resistance before and after the test according to the method in clause 9-1-1 by using accommodated conductor in clause 5. 2)One cycle of temperature is as follow and test 5 cycles. <u>Step Temp.(°C) Time(min.)</u> <u>1 -55±3 30</u> <u>2 25±2 2 ~3</u> <u>3 85±2 30</u> <u>4 25±2 2 ~3</u> 3)Expose conductor and connector in mated condition and leave them under normal temperature.	 Initial contact resistance : Less than 30mΩ Contact resistance after the test : Less than 50mΩ Free from any defect such as crack, warping and deformation etc. on each portion the connector.

9-4. Other j	performance
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No.	Test Item	Test Method	Requirements			
9-4-1	Soldering (Resistance to reflow soldering)	 Solder by setting reflow bath on the following condition. Preheating: 150±10°C, 60~120 s Soldering: 240±5°C, 30±1s NOTE: Temperature must be measured at contact terminal portion and peak temperature on the upper surface of P.C.B must be less than 260°C. Solder paste to be used is JIS Z 3282 H60A or H63A. Soldering particle is more than 200 mesh and flux is inactive rosin family flux. 	 Contact resistance after the test: Less than 50mΩ Insulation resistance after the test: More than 100MΩ No short circuit and insulation breakdown for dielectric withstanding voltage test after this test. Free from any damage on performance and contact performance after soldering. 			

No.	Test Item	Test Method	Requirements
9-4-2	Soldering (Solderability) (Reflow)	 Solder by setting reflow bath on the following condition. Preheating:150±10°C, 60~120 s Soldering:215±5°C, 10±1s NOTE: Temperature must be measured at contact terminal portion and peak temperature on the upper surface of P.C.B must be less than 260°C. Solder paste to be used is JIS Z 3282 H60A or H63A. Soldering particle is more than 200 mesh and flux is inactive rosin family flux. 	1)Actual soldered area must be more than 90% of the dipped area intended to be soldered.
9-4-3	Conductor retention force (Reference)	1)Measure initial retention force after inserted and locked by using accommodated conductor specified in clause 5.	 More than 0.88N/contact for FPC (More than 90g/contact for FPC) More than 0.68N/contact for FFC (More than 70g/contact for FFC)

10. INDICATION AND PACKAGING

10-1. Indication

- 1) Catalog number and lot number are not be indicated on the connector.
- 2) Catalog number and quantity shall be indicated on the surface of the package box.

10-2. Packaging

 The connector individuals are packed by tapes with specified quantity in accordance with [JIS C 0806"Packaging of Electronic Components on Continuous Tapes (Surface Mount components)"] and put into package box in accordance with FCI JAPAN packaging specification.

11. Remarks

- 11-1. Please refer to the "Handing procedures and remarks" before use.
- 11-2. Retention force for accommodated conductor specified in clause 9-4-3 differs due to it's kind, structure and surface treatment of conductor. Therefore, the value of retention force specified in the clause for performance is reference value.
- 11-3. Since this connector can not be used for CIC (Conductor such as silver paste, carbon etc.) as accommodated conductor, please consult us separately.